

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A semiconductor power module, comprising:
a lead frame having a first portion at a first level, a second portion ~~connected to~~
surrounding the first portion at a second level, and a plurality of terminals connected to the
second portion, wherein the first and the second portions and the terminals are made of one
body;
a power circuit mounted on a first surface of the first portion;
a control circuit mounted on the first surface of the first portion or the second portion
that drives the power circuit;
a heat detection circuit mounted on the first surface of the first portion that detects the
heat produced by the power circuit;
a heat sink having an electrically insulating property and thermal conductivity,
wherein the heat sink has a first surface adjacent to a second surface of the first portion, and a
second surface opposite to the first surface and exposed to the outside ~~directly contacts a~~
~~second surface opposite the first surface of the first portion of the lead frame and wherein a~~
~~surface of the heat sink is exposed to the outside of the semiconductor power module~~; and
a sealer having an electrically insulating property and thermal conductivity, wherein
the sealer covers the power circuit.

Claim 2 (Original): The semiconductor power module of claim 1, wherein the first
portion of the lead frame is centrally positioned within the lead frame.

Claim 3 (Original): The semiconductor power module of claim 1, wherein the power
circuit includes a power semiconductor element.

Claim 4 (Original): The semiconductor power module of claim 1, wherein the first surface of the first portion is a top surface and wherein the second surface of the first portion is a bottom surface.

Claims 5-7 (Cancelled).

Claim 8 (Previously presented): The semiconductor power module of claim 1, wherein the heat sink is adhered to at least one of the lead frame and the sealer with an adhesive.

Claim 9 (Original): The semiconductor power module of claim 8, wherein the adhesive contains a filler that includes at least one compound selected from the group consisting of Al_2O_3 , AlN and BeO.

Claim 10 (Previously presented): The semiconductor power module of claim 1, wherein the heat sink and the sealer each have grooves or rings and wherein the heat sink and the sealer are connected to each other by means of the grooves or the rings.

Claim 11 (Previously presented): The semiconductor power module of claim 1, wherein the heat sink is sheet-shaped.

Claims 12-21 (Cancelled).

Claim 22 (Previously Presented): The semiconductor power module of claim 1, wherein the heat sink comprises at least one compound selected from the group consisting of AlN and BeO.